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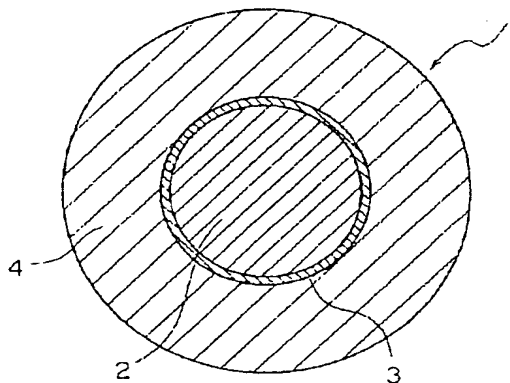
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**(54) SEMICONDUCTOR PACKAGE AND ITS
MANUFACTURING METHOD**

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a composite microball that has at least 20 μm solder at the outer periphery of a core ball and its manufacturing method, and a semiconductor package that mounts a semiconductor device by using the composite microball.

SOLUTION: In the package of a semiconductor device that mounts the semiconductor device and at the same time the microball as an electric contact, the microball consists of a composite microball 1 having a conductive film around a core ball 2, the core ball has a diameter of 30 to 100 μm , a sufficiently excellent rolling property, a superior diameter accuracy, and the conductive film has a solder plated layer 4 that is uniformly formed on an outer-periphery surface and has a thickness of 10 μm or more, mounts the composite microball 1, and can accurately control the dimension accuracy of a Z shaft of the package.



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